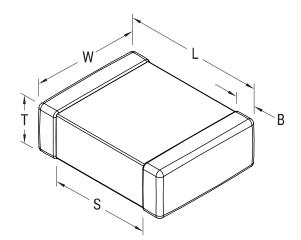


## C1812C911MATAC7210

SMD Comm X8G HT150C, Ceramic, 910 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

0.1% 1 MHz 1.0Vrms

100 GOhms

0% Loss/Decade Hour: Referee Time is 1000 Hours

		Specifications	
	1812	Capacitance	910 pF
	4.5mm +/-0.3mm	Measurement Condition	1 MHz 1.0Vrms
	3.2mm +/-0.3mm	Tolerance	20%
	1mm +/-0.10mm	Voltage DC	250 VDC
	2.3mm MIN	Dielectric Withstanding Voltage	625 VDC
	0.6mm +/-0.35mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
s		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
	4000	,, , , ,	

**Dissipation Factor** 

Insulation Resistance

Aging Rate

Dimensions Chip Size L W Т s в

## **Packaging Specifications** Pac

	e
Packaging Quantity 4000	

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